



Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **F0112-02** DATE: 12/20/2001

Product Affected: NW6002CS, NW6005AS, NW6006AS

Date Effective: 04/01/2002

MEANS OF DISTINGUISHING CHANGED DEVICES:

- ☒ Product Mark
☐ Back Mark
☐ Date Code
☐ Other

Contact: Dasharath Patel

Title: QA Manager, FIFO/Telecom Products

Phone #: (408) 330-1488

Fax #: (408) 330-1450

E-mail: dasharath.patel@idt.com

Attachment: ☒ Yes ☐ No

Samples: Available upon request

DESCRIPTION AND PURPOSE OF CHANGE:

- ☐ Die Technology
☐ Wafer Fabrication Process
☒ Assembly Process
☒ Equipment
☒ Material
☒ Testing
☒ Manufacturing Site
☐ Data Sheet
☒ Other

Packing and Orientation

This PCN is an addendum to PCN # F0107-02

Devices affected: NW6002, NW6005, NW6006

As a result of Integrated Device Technology, Inc (IDT) acquisition of Newave Semiconductor Corp., USA, there will be a consolidation of operations. This will consist of assembly, test, backend and packing changes. Please see attachments for a detailed description of these changes.

RELIABILITY/QUALIFICATION SUMMARY: Available upon completion of qualification process.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____

☐ **Approval for shipments prior to effective date.**

Name/Date: _____

E-Mail Address: _____

Title: _____

Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____

DATE: _____



Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT - PCN #: F0112-02

PCN Type: Assembly, Test, Backend and Packing changes

Data Sheet Change: No change

Detail of Change: See attached

Conversion schedule (Estimated) 01-Apr-02



Attachment
PCN F0112-02

Description of Changes

This PCN is an addendum to PCN F0107-02 for devices NW6002CS, NW6005AS and NW6006AS.

The following additional changes will be implemented on all these products:

Manufacturing Site Change:

Newave assembly, test and backend facilities will be transferred selectively to IDT ISO 9001 & 9002 certified assembly, test and backend facilities. For the devices mentioned above, this will now also include IDT-Philippines

Manufacturing Site Change:

Effective April 1st, 2002, customers can receive devices also assembled at IDT, Philippines.



In addition to changes
detailed on PCN F0107-02

Device Name	Assembly Location		
	From	To	To
NW6005AS	OSET	Unisem/AMKOR IDT-Philippines	IDT-Philippines

Device Name	Assembly Location		
	From	To	To
NW6006AS	OSET	Unisem/AMKOR IDT-Philippines	IDT-Philippines

Device Name	Assembly Location		
	From	To	To
NW6002CS	OSET	AMKOR	Unisem



Manufacturing Site Change

Assembly Location

ASAT, Hong Kong
AMKOR Tech, Philippines
AMKOR Tech, Buchon, Korea
AMKOR Tech, Bupyung, Korea
AMKOR Tech, Kwangju, Korea
AMKOR Tech, Seoul, Korea
UNISEM, Malaysia
IDT, Philippines

Assembly lot# contains letter

T
P
N
Y
D
I
Z
K

Mark/Test/Backend locations

IDT Penang
IDT, Philippines
Unisem
Amkor Tech, Korea
ASAT, Hong Kong
Amkor Tech, Philippines
IDT, Philippines

Top mark date code contains letter

P
M
U
A
X
D
M